ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN16790XKA
Issue Date: 23 December 2016

Title of Change:	Final PCN for wafer fabrication site transfer to ON Semiconductor Niigata Co., Ltd. In Niigata, Japan (Group KA)
Proposed first ship date:	23 March 2017 or earlier upon customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasunari.Noguchi@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ON Niigata, Japan ☐ External Foundry/Subcon site(s)

Description and Purpose:

This is a Final Process Change Notification to announce the addition of a new wafer fabrication site for the device covered in this notice. Device formerly manufactured at the Manufacturers AMPI will be manufactured at ON Semiconductor Niigata Co., Ltd. (OSNC) following the expiration of this notice. OSNC located in Niigata, Japan has obtained ISO9001 certification.

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed to check the device functionality and electrical specifications.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

Reliability Data Summary:

QV DEVICE NAME SFT1345-TL-H
PACKAGE: TP-FA

Test	Specification	Condition	Interval	Result
HTRB	JESD22-A108	Ta=150℃, 80% max rated VDSS	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150℃, 100% max rated VGSS	1008 hrs	0/231
SSOL	JESD22-A108	Tj= 150°C	1008 hrs	0/75
AC	JESD22-A102	Ta = 121°C, 100% RH, 15psig	96 hrs	0/231
TC	JESD22-A104	Ta= -55℃ to +150℃	100 cyc	0/75
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, 80% max rated VDSS	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260℃	-	-
RSH	JESD22- B106	Ta = 265℃, 10 sec	-	0/90

QV DEVICE NAME SFT1445-TL-H
PACKAGE: TP-FA

Test	Specification	Condition	Interval	Result
HTRB	JESD22-A108	Ta=150℃, 80% max rated VDSS	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150℃, 100% max rated VGSS	1008 hrs	0/231
SSOL	JESD22-A108	Tj= 150°C	1008 hrs	0/75
AC	JESD22-A102	Ta = 121°C, 100% RH, 15psig	96 hrs	0/231
TC	JESD22-A104	Ta= -55℃ to +150℃	100 cyc	0/75
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, 80% max rated VDSS	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260℃	-	-
RSH	JESD22- B106	Ta = 265℃, 10 sec	-	0/90

Electrical Characteristic Summary:
There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of affected Standard Parts:

Part Number	Qualification Vehicle
SFT1345-H	SFT1345-TL-H
SFT1345-TL-H	SFT1345-TL-H
SFT1445-H	SFT1445-TL-H
SFT1445-TL-H	SFT1445-TL-H